



## Description

PBGA is a die-up design, plastic overmolded BGA using 2 or 4 Layer BT substrate.

PBGA are the most popular packages with high I/Os. PBGAs also have a good thermal and electrical performances.

Signetics's PBGA offers improved electrical and thermal operation such as POWER and GND planes.

HSPBGA packages can be used for high performance applications with high I/O connections and high thermal and electrical requirements.

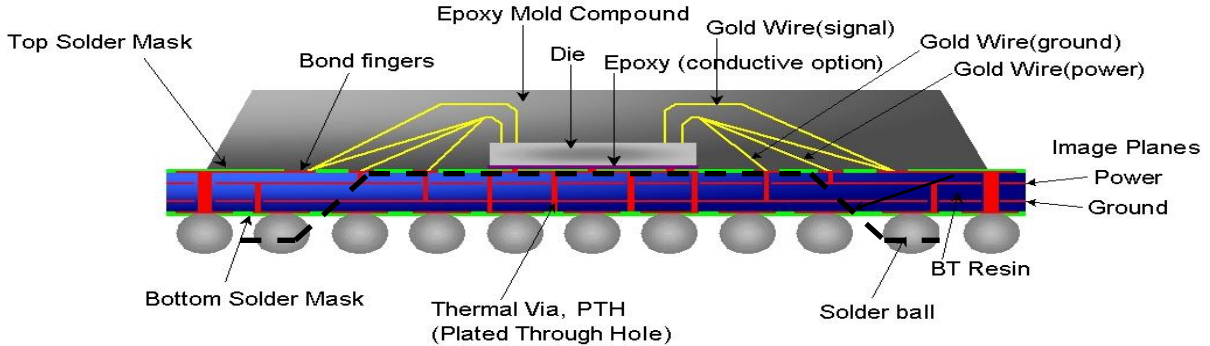
## Features

- Up to 37.5mm body size
- 1.00mm and 1.27mm ball pitch options
- Multiple power and ground potentials
- Conductive epoxy option
- Stacked and Multi-die variations
- Standard and custom ball arrays
- Multi-layer configurations for optimal electrical performance
- Standard, Pb-Free, RoHS compliant and Green BOMs
- HSPBGA - Exposed heat spreader option for increased thermal performance

## Applications

- Devices with high I/Os
- Graphics Processing Units
- Requiring improved portability such as laptop PC's

<b>Package Sizes</b>	17x17mm – 37.5x37.5mm
<b>I/O Counts</b>	208 - 816



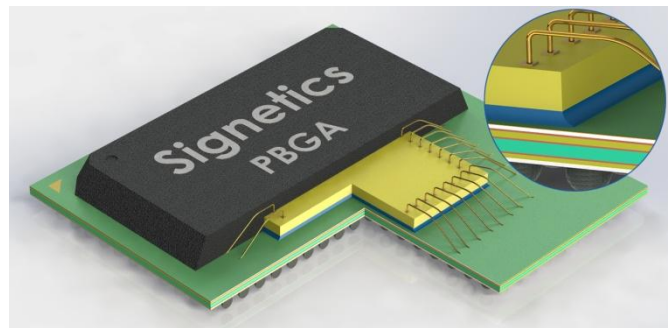
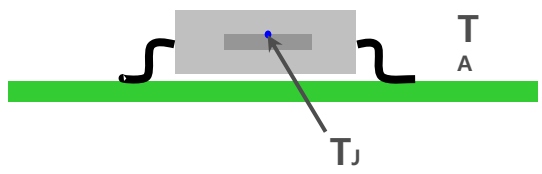
## Reliability

<b>MSL Level</b>	JEDEC Level 3,
<b>Temp Cycling</b>	150C/-65C, 1000 cycles
<b>Unbiased HAST</b>	130°C/85% RH, 2 atm, 96hrs
<b>High Temp Storage</b>	150°C, 1000hrs

## Thermal Data

BODY SIZE	Ball Count	Theta JA (°c/w)
23X23mm	420B	21.09
23X23mm – HS	420B	19.27
27X27mm	622B	15.84
27X27mm-HS	622B	13.98

• JEDEC STD 2S2P PCB, Still air



## Electrical Data

- 23X23mm Body, 289B
- Simulation Frequency : 100MHz

<b>Resistance (mΩ)</b>	180~570
<b>Inductance (nH)</b>	3.5~14.5
<b>Capacitance (pF)</b>	1.2~3.8

• Results dependent on body size, die size, and Substrate design etc..

